# EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| S3 | 145 | ("204" "205").clas. and frame and base and spring with (electrical electrode) and seal | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/05 16:21 |
| S2 | 232 | ("204" "205").clas. and frame and base and spring with (electrical electrode) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/05 16:21 |
| S4 | 1 | ("204" "205").clas. and frame and base and spring with (electrical electrode) and seal and thrust adj plate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/05 16:23 |
| S7 | 40 | ("204" "205").clas. and spring with (electrical electrode) and seal$4 and ((thrust adj plate) (backing adj plate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/05 16:24 |
| S6 | 2 | ("204" "205").clas. and spring with (electrical electrode) and seal$4 and thrust adj plate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/05 16:24 |
| S5 | 2 | ("204" "205").clas. and spring with (electrical electrode) and seal and thrust adj plate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/05 16:24 |
| S8 | 477 | ("204" "205").clas. and frame and base and spring and (semiconductor wafer microelectronic microfeature electronic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 13:54 |
| S1 | 852 | ("204" "205").clas. and frame and base and spring | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 13:54 |
| S9 | 299 | ("204" "205").clas. and frame and base and spring and (semiconductor wafer microelectronic microfeature electronic) and copper | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 13:55 |

# EAST Search History

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|---|---|---|---|---|---|---|
| S13 | 4 | ("5227041".pn.) "6139712".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:20 |
| S12 | 5 | ("5227041".pn.) "9925905" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:20 |
| S11 | 4 | ("6540899" "6399479").pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:20 |
| S10 | 198 | ("204" "205").clas. and frame and base and spring and (semiconductor wafer microelectronic microfeature electronic) and copper and anode and cathode | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:22 |
| S14 | 3 | ("204" "205").clas. and (semiconductor wafer microelectronic microfeature electronic) and copper and anode and cathode and distribut$ with force with seal$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:25 |
| S15 | 12 | ("204" "205").clas. and anode and cathode and distribut$ with force with seal$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:30 |
| S16 | 1 | (204/297.09 204/297.1).ccls. and distribut$ with force with seal$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:33 |
| S18 | 2 | "20050092614".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:46 |
| S17 | 280 | (204/297.09 204/297.1).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/08 14:46 |
| S19 | 4 | ("6495007" "6749728").pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/09 13:26 |

# EAST Search History

| S20 | 4 | jorne.in. and electroplating | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/10/10 10:40 |
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